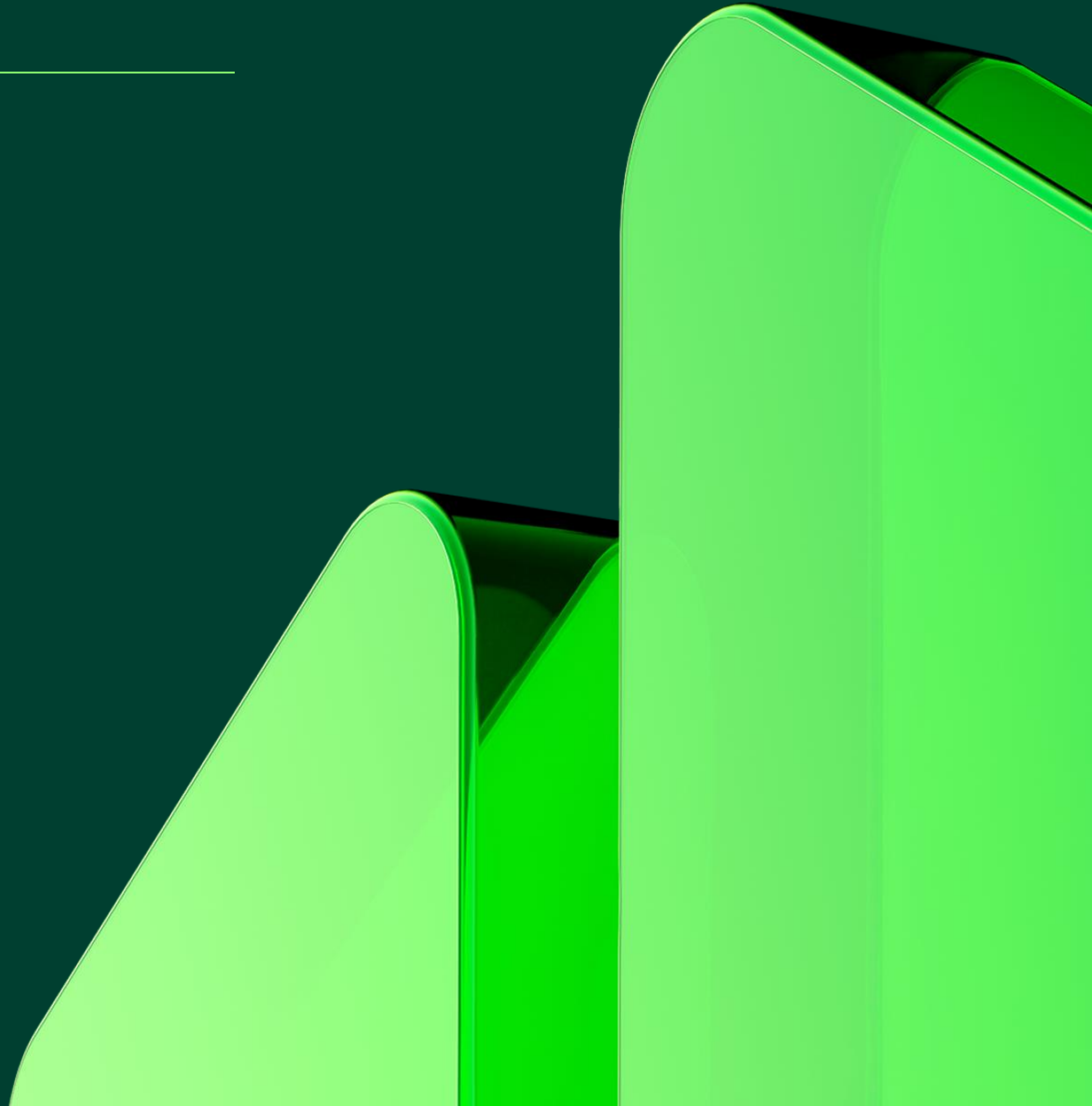
SUSS

April 2, 2025

Investor Presentation

Metzler Small Cap Days 2025

Frankfurt



SUSS at a glance

- Hidden champion headquartered in Germany with 75 years track record of innovation and growth
- Key technology provider for semiconductor frontend and advanced backend industry, benefiting from structural growth drivers such as Artificial Intelligence
- Global customer base with largest share of business in Asia
- Strategic partner for global semiconductor IDMs and foundries
- Innovator with relevant network to research institutes and universities

SUSS is part of our digital life!

Management Board of SUSS MicroTec SE

CFO

Dr. Cornelia Ballwiesser

- Finance & Controlling
- Legal & Compliance
- Risk Management
- Investor Relations
- IT
- ESG

CEO

Burkhardt Frick

- Sales and Service
- Strategy
- HR
- Internal Audit
- Business Units:
  Advanced Backend Solutions,
  Photomask Solutions

COO

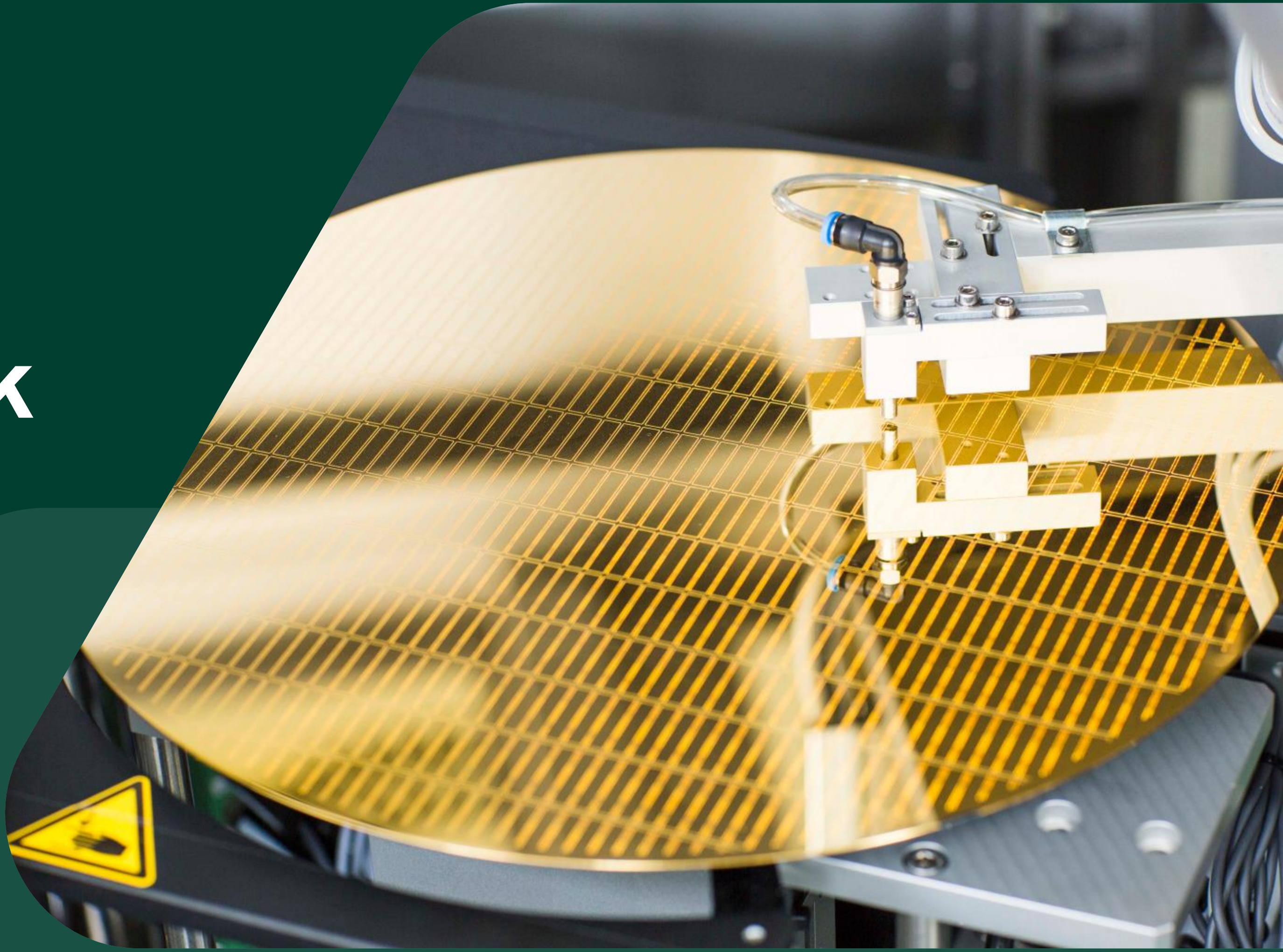
Dr. Thomas Rohe

- R&D
- Purchasing
- Production
- Logistics
- Quality Management
- Product Center
- Facility Management

Our corporate vision defines our strategies

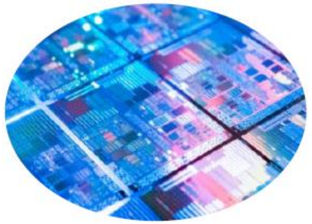
Leader in enabling innovative advanced backend & photomask solutions

Our vision



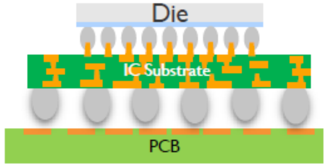
Our world are the semiconductor frontend and backend process steps

Wafer fabrication



Front-end-of-line Wafer process

- Deposition/coating
- Cleaning
- **Patterning/lithography**[1]
- Etching
- Implantation
- Annealing
- **Permanent bonding**
- **Temporary bonding**
- CMP polishing



From middle-of-line to back-end-of-line

Advanced packaging

- Deposition/coating
- Cleaning
- **Patterning/lithography**
- Etching
- Annealing
- CMP polishing
- **Permanent bonding**
- **Temporary bonding**
- **Wafer level packaging**
- Wafer dicing
- Panel-level packaging

Final packaging

- Mounting
- Wire bonding
- Molding encapsulation
- Trim & forming

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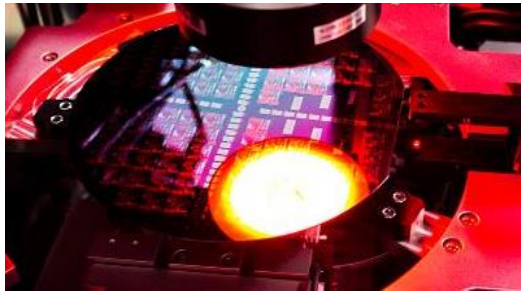
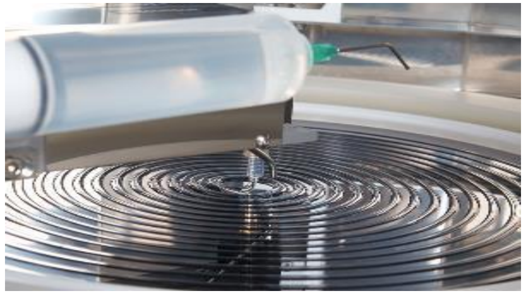
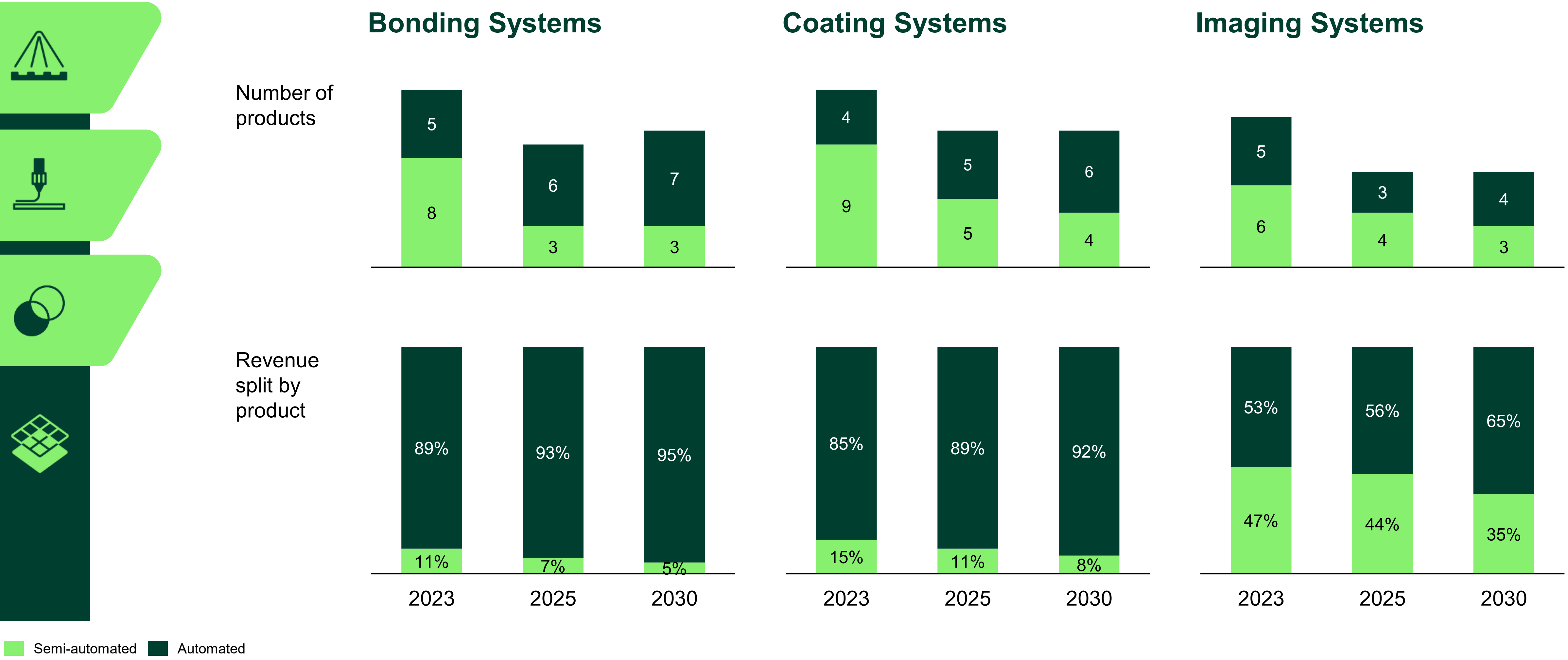
[1] Only related to Photomask processing

Source: Yole, Lithography and Bonding Equipment for More than Moore 2022

Our two segments, mainly serving the semiconductor industry

	Frontend	Advanced Backend		
Segments	Photomask Solutions	Advanced Backend Solutions		
				
Products	**Photomask Equipment**  MaskTrack X	**Imaging** Mask Aligner MA200/300   UV Projection Scanner DSC300	**Coating**  ACS300	**Bonding** XBC300   XB8

Focus on high-volume manufacturing markets while semi-automated tools will be phased-out during next years in Advanced Backend Solutions business unit



Full range of bonding solutions by SUSS

Temporary Bonding	Permanent Bonding	Hybrid Bonding	
Temporary Bonding XBS300 	Bonding (200 mm) XBS200 	W2W (up to 200 mm) XBS200 	W2W (up to 300 mm) XBS300 W2W 
De-bonding/Cleaning XBC300 Gen2 		D2W & W2W XBC300 Gen2 D2W/W2W 	D2W XBC300 Gen2 D2W 
Mech. De-bonding (semi-auto) DB12T 	High-force Bonding (semi-auto) SB8 Gen2/XB8 		

SUSS hybrid bonding solutions – understanding customer's needs

Wafer-to-wafer HB
XBS300 W2W

Product launch: 10/2022
Target customers: HVM

Die-to-wafer/wafer-to-wafer HB
XBC300 Gen2 D2W/W2W

Product launch: 05/2024
Target customers: Research institutes, R&D teams of HVM

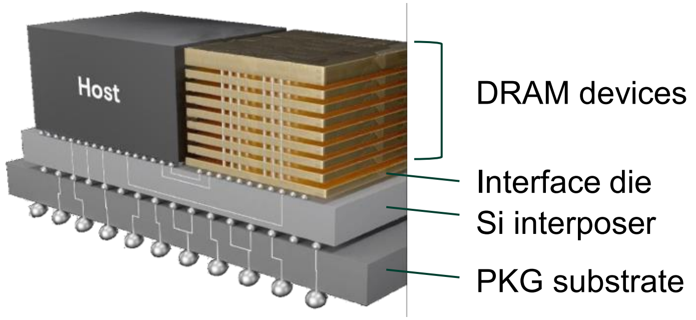
Die-to-wafer HB
XBC300 Gen2 D2W

Product launch: H1/2025
Target customers: HVM

We optimize our product solutions to serve our customer's device and manufacturing needs.

HBM roadmap enables SUSS to grow in existing and new markets

in € million	HBM3E	HBM4	HBM4E	HBM5
Expected SOP	2024	2025	2026 or 2027	2027 or 2028
# of DRAM layer acc. to JEDEC	8/12	12	16	16/20
Bonding type in DRAM stack	TCB	TCB	TCB or HB	HB
Thinning of DRAM devices	TBDB	TBDB	TBDB	TBDB



source: Micron, HBM3E

Relevance for SUSS:

1. TBDB remains a crucial process for thinning of DRAM devices used in HBM cube

   Growth of existing SUSS TBDB business in line with general HBM market growth

2. Increase of layer number in HBM cube triggers more TBDB capacity for thinning of DRAM devices

   Additional growth of SUSS TBDB business in line with higher layer in HBM cube

3. Hybrid bonding will gradually replace Thermal Compression bonding for stacking of DRAM devices

   Expansion into this market offers new growth opportunities with SUSS HB solutions

TCB: Thermal compression bonding, HB: hybrid bonding, TBDB: Temporary bonding & de-bonding

We have built up additional temporary bonding capacity in Taiwan

- We added 50+ people in Hsinchu in order increase manufacturing capacity for temporary bonders
- First temporary bonder ‘made in Taiwan’ has been completed at the beginning of March 2024
- Full capacity available since Q3-2024
- Total manufacturing capacity for temporary bonding equipment (bonder, debonder and cleaner) in Sternenfels and Hsinchu allows us to generate yearly sales of ~ €150 million

New, larger production site in Zhubei (Taiwan) prepares us for further targeted growth

1

Signing

of long-term lease agreement for new production site in Zhubei took place on October 23, 2024.

2

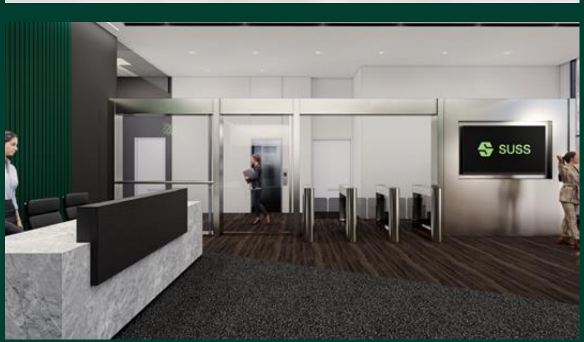
Completion

of shell is scheduled for the end of 2024. We will then carry out cleanroom and office installations with expected CAPEX of € 15-20 million.

3

Production start

at the new site is expected in the second half of 2025. The new factory offers the potential to double production capacity under clean room conditions to ~6,300 m².



SUSS reached new highs for sales and profitability in 2024

Financial Results

FY 2024

423.7
in € million
Order intake
FY 2024
+0.8% YoY

446.1
in € million
Sales
FY 2024
+46.6% YoY

40.0
in %
Gross profit margin
FY 2024
+5.9pp YoY

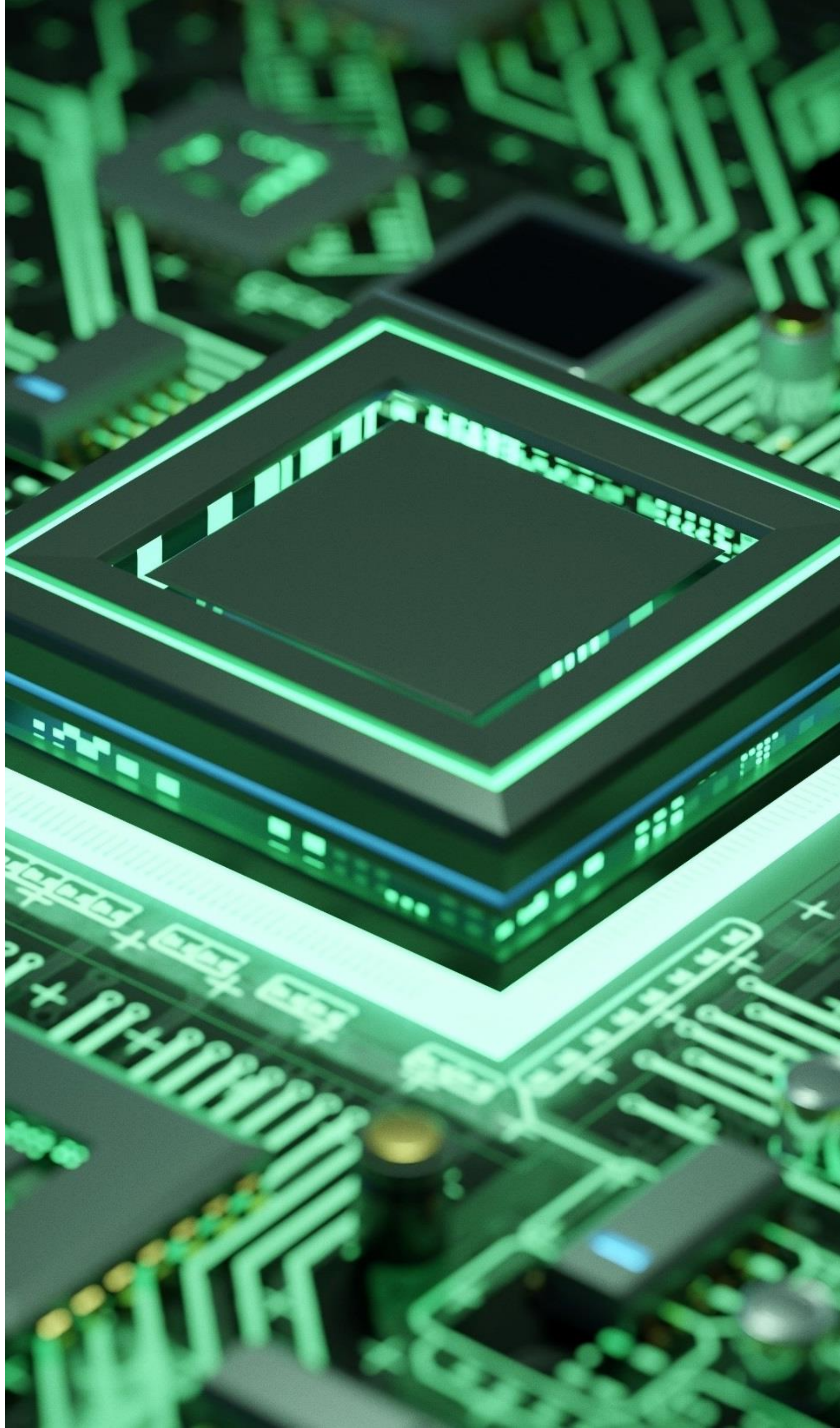
16.8
in %
EBIT margin
FY 2024
+7.7pp YoY

Key CEO messages

Record order intake in Q4 2024 (€ 147.5 million) driven by both segments, mainly to support capacity expansion at key customers while demand for Coating systems continued to improve. Based on total order intake of € 423.7 million, book-to-bill ratio was solid at 0.95 in 2024 as a whole.

Thanks to outstanding execution and based on increased capacity, Operations enabled record sales of € 150.8 million in Q4 2024 and total sales of € 446.1 million in 2024. We have built and delivered more tools than ever before.

Profitability improved significantly in 2024. Main driver for the high gross profit margin of 40.0% and EBIT margin of 16.8% was a very favorable product and customer mix as well as the higher business volume.



Strong growth and improved profitability made 2024 the most successful year in SUSS' history

SUSS

in € million	FY 2024	FY 2023	Change
Order intake	423.7	420.5	+ 0.8%
Order book as of December 31	428.4	452.5	- 5.3%
Sales	446.1	304.3	+ 46.6%
Gross profit	178.3	103.9	+ 71.6%
Gross profit margin	40.0%	34.1%	+ 5.9pp
EBIT	75.1	27.8	+ 170.1%
EBIT margin	16.8%	9.1%	+ 7.7pp
Earnings after taxes (continuing operations)	52.1	17.3	+ 201.2%
Net profit[1]	110.3	4.7	n/a
EPS basic (in €, continuing operations)	2.72	0.91	+ 198.9%
EPS basic (in €)[1]	5.77	0.25	n/a
Net cash	122.9	32.8	+ 274.7%
Free cash flow (continuing operations)	25.3	7.9	+ 220.3%
Free cash flow total[1]	96.1	-4.4	n/a
Investments	7.6	4.6	+65.2%
Dividend proposal (in €)	0.30	0.20	+50.0%
Employees as of December 31	1,498	1,207	+ 24.1%

[1] including discontinued operations, i.e. MicroOptics business

- Order intake slightly up year-on-year and managed to offset the decline in demand from China (€ -41.4 million)
- Gross profit margin increased significantly by 5.9pp year-on-year, benefiting from favorable product and customer mix and was volume driven in both segments; EBIT margin also benefited from the under-proportional increase in OPEX (OPEX ratio was 22.8% of sales vs. 25.3% in 2023)
- Net profit of € 110.3 million includes result from discontinued operations (€ 58.3 million), i.e. the sale of our MicroOptics business
- Dividend proposed to increase by 50% to € 0.30 per share, which would correspond to our growth and is approximately 23% of the free cash flow from continuing operations

High continuity in profitability

SUSS

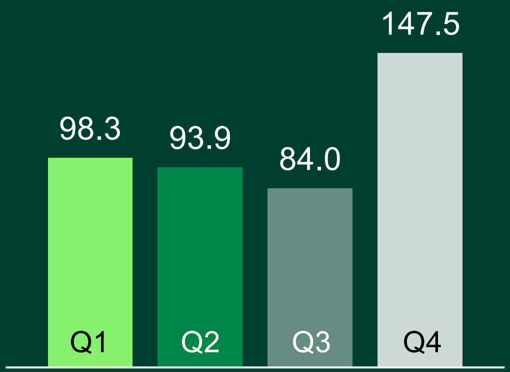
On Group level, gross profit margin above 39% and EBIT margin above 15% in all four quarters

€423.7m
Order intake 2024

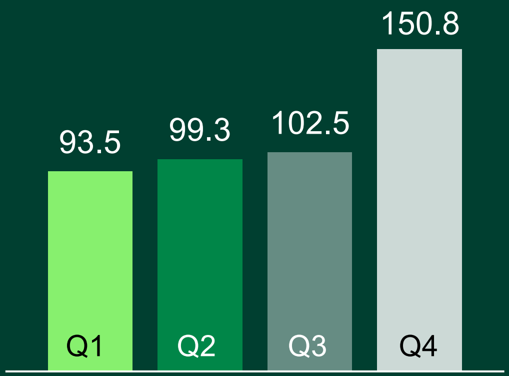
€446.1m
Sales 2024

40.0%
Gross profit margin 2024

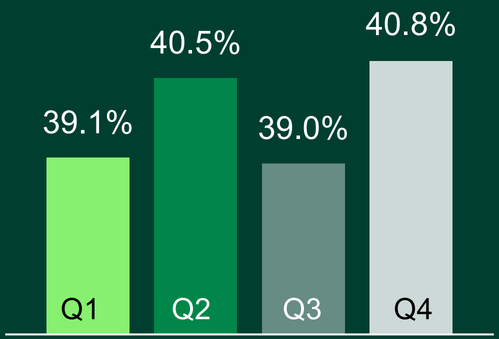
16.8%
EBIT margin 2024



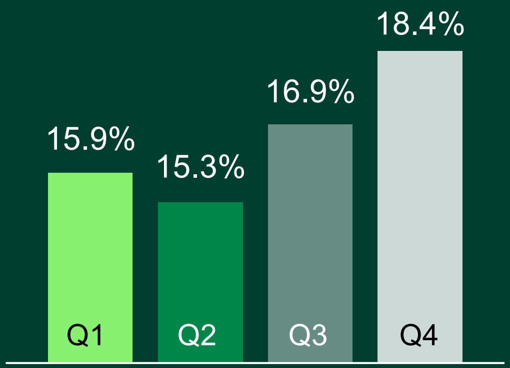
Order intake by quarters



Sales by quarters



Gross profit margin by quarters



EBIT margin by quarters

Segment Overview FY 2024

Advanced Backend Solutions

in € million	FY 2024	FY 2023
Order intake	300.2	294.4
Order book	271.7	286.8
Sales	314.7	214.7
Gross profit	132.8	77.8
Gross profit margin	42.2%	36.2%
EBIT	60.5	20.1
EBIT margin	19.2%	9.4%

- Very high order intake of the previous year once again exceeded by 2%; combined orders in connection with AI applications for temporary bonding solutions and UV projection scanners at around previous year's level; Coating systems order intake improved in H2 2024
- Significant sales growth of € 100.0 million or 46.6% year-on-year, mainly driven by execution of AI-connected bonder orders; bonder sales thus more than tripled year-on-year
- Gross profit margin improved by 6.0pp to 42.2% thanks to high sales volume and favorable product and customer mix

Photomask Solutions

in € million	FY 2024	FY 2023
Order intake	123.5	124.1
Order book	156.7	165.7
Sales	131.4	89.7
Gross profit	47.4	26.5
Gross profit margin	36.1%	29.5%
EBIT	27.2	12.4
EBIT margin	20.7%	13.8%

- Expected normalization of orders from China (- €15.8 million year-on-year) was almost offset by other global markets to reach almost stable order intake
- Strong order book level of ~ € 157 million provides high visibility and capacity utilization in 2025
- Sales growth of 46.5% was realized by increasing the number of slots, additional staff and shortening lead times
- Gross profit margin and EBIT margin benefited from strong product and customer mix as well as from very high business volume

Segment ABS constantly achieved gross profit margin of at least 40%; PS with EBIT margin > 20% in three out of four quarters

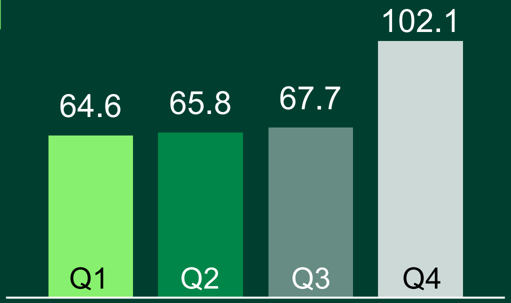
€423.7m
Order intake 2024

€446.1m
Sales 2024

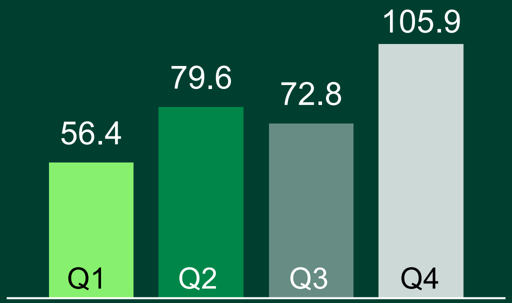
40.0%
Gross profit margin 2024

16.8%
EBIT margin 2024

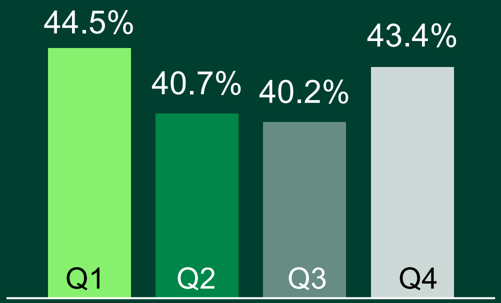
Advanced Backend Solutions (ABS)



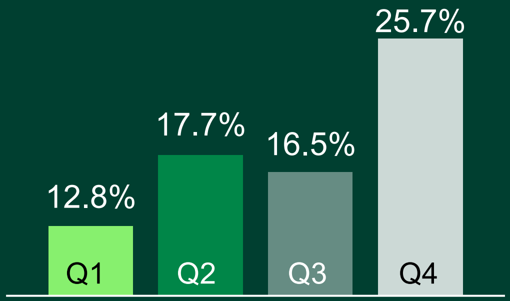
Order intake by quarters



Sales by quarters

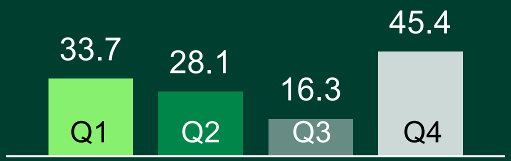


Gross profit margin by quarters

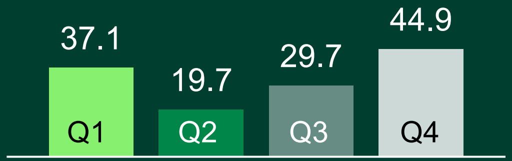


EBIT margin by quarters

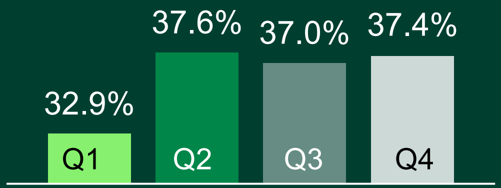
Photomask Solutions (PS)



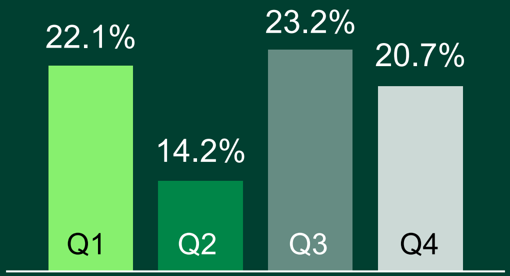
Order intake by quarters



Sales by quarters



Gross profit margin by quarters



EBIT margin by quarters

Order book at year-end 2024 and several H1 orders to be executed this year provide very solid base for 2025

SUSS

Order book as of December 31, 2024,
of which the **vast majority** is expected to be executed in 2025

€ 428.4 million

Additional H1 orders, especially for our Advanced Backend Solutions with shorter lead times, are scheduled to be executed in 2025

€ 60–100 million

SUSS expects to continue its growth trajectory in 2025

Guidance 2025

(as of March 27, 2025)

Sales

in € million

470–510

Actual 2024:
€ 446.1 million

Gross profit margin

in %

39–41

Actual 2024:
40.0%

EBIT margin

in %

15–17

Actual 2024:
16.8%

Expected development in our segments

Advanced Backend Solutions

Sales expectation

Growth in the mid single-digit percentage range

Profitability expectation

Slight decline in gross profit margin and EBIT margin due to minor change in product/customer mix and higher R&D expenses

Photomask Solutions

Sales expectation

Growth of 10 to 20 % year-on-year

Profitability expectation

Higher sales volume and better product and customer mix is expected to positively impact gross profit margin and EBIT margin

Market Demand Outlook

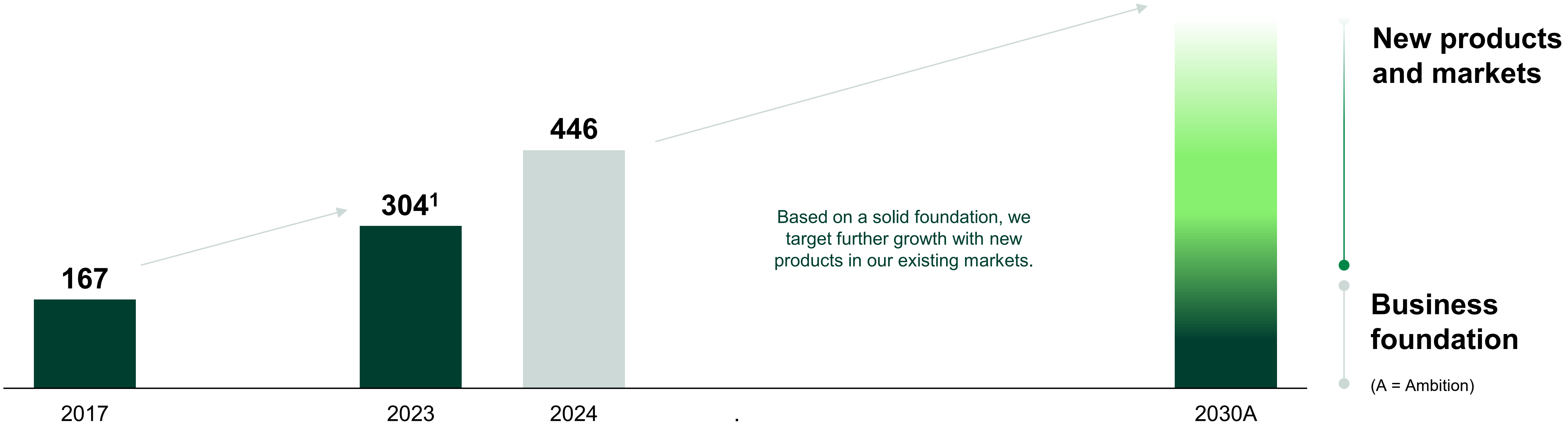
Imaging Systems: Higher demand compared to 2024 expected, especially for our UV projection scanner (linked to CoWoS)

Coating Systems: Improved order situation in the second half of 2024 is expected to continue in 2025, e.g., due to foundry and OSAT customers

Bonding Systems: Slight decline in order intake expected as follow-up orders cannot keep pace with the initial capacity build-up of the last two years

- New business expected slightly below 2024 level due to normalized demand from China
- Additional momentum from the launch of our new high-end cleaner and a new mid-end cleaner, both planned for 2026, is anticipated towards the end of 2025 at the earliest

Based on our business foundation we see further potential beyond



Based on a solid foundation, we target further growth with new products in our existing markets.

1

Major growth drivers 2023

Converting high order backlog in Photomask Solutions and Bonder business into sales growth

2

Major growth drivers 2024

- Bonding (especially with regard to AI-driven demand for temporary bonders)
- Photomask Solutions

3

Major growth drivers 2030

- General expected market growth in our core businesses (lithography, bonding, photomask)
- Hybrid Bonding
- Wafer Cleaning

1 Excluding MicroOptics

Investor Relations information

Conference and Roadshow Calendar

April 2, 2025
Metzler Small Cap Days, Frankfurt (IR-only)

May 21, 2025
Chicago Roadshow, hosted by Jefferies

May 22, 2025
Berenberg European Conference, New York City

May 27, 2025
db European Champions Conference, Frankfurt

June 12, 2025
Warburg Highlights Conference, Hamburg

November 17, 2025
SUSS Capital Markets Day, Garching/Munich

There may be changes to the SUSS conference and roadshow schedule.

Financial Calendar

May 8, 2025
Q1 Report 2025

June 3, 2025
Annual General Meeting

August 7, 2025
Half Year Report 2025

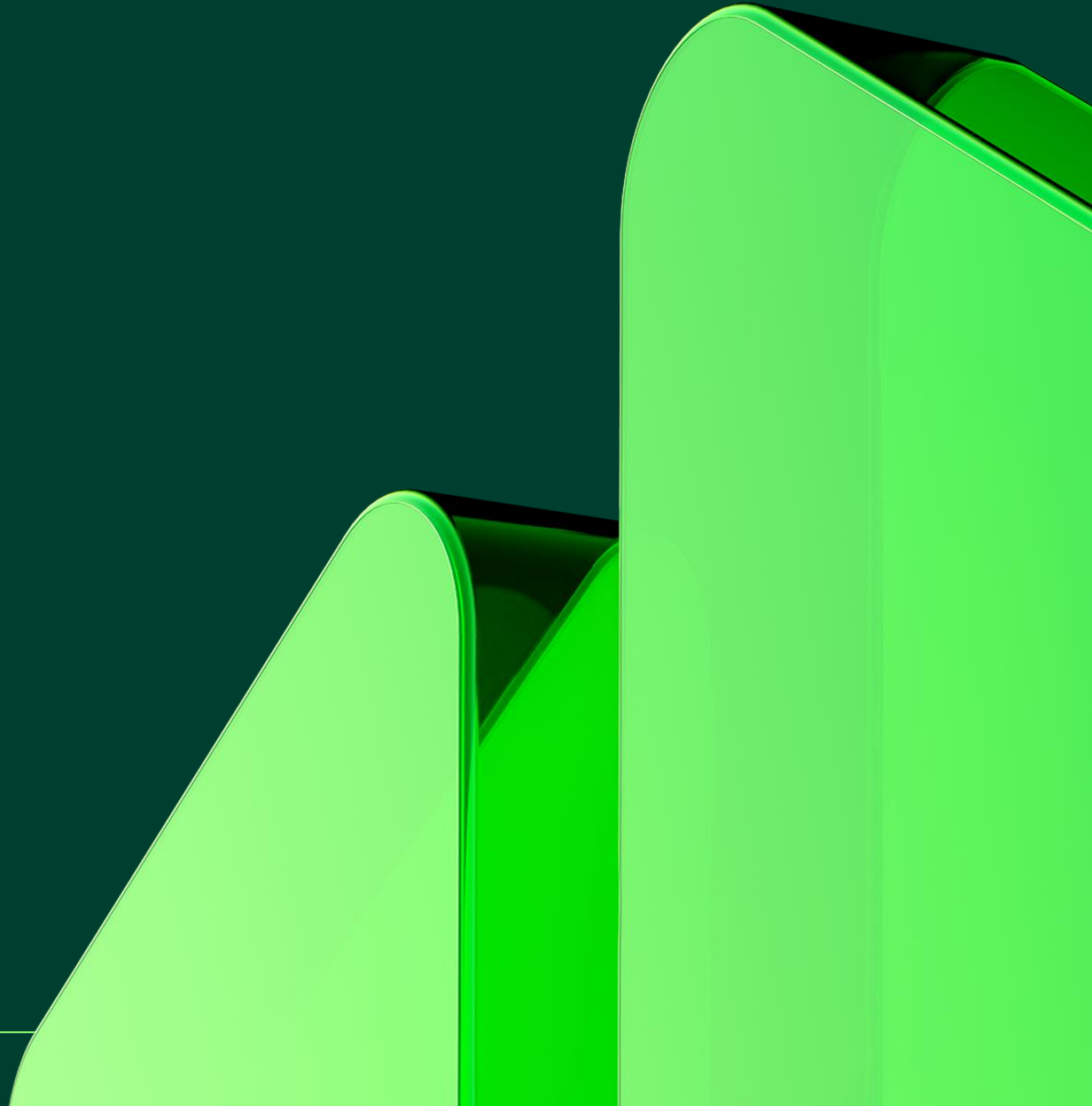
November 6, 2025
Q3 Report 2025

Disclaimer

This presentation contains forward-looking statements relating to the business. financial performance and earnings of SUSS MicroTec SE and its subsidiaries and associates.

Forward-looking statements are based on current plans. estimates. projections and expectations and are therefore subject to risks and uncertainties. most of which are difficult to estimate and which in general are beyond the control of SUSS MicroTec SE. Consequently. actual developments as well as actual earnings and performance may differ materially from those which explicitly or implicitly assumed in the forward-looking statements.

SUSS MicroTec SE does not intend or accept any obligation to publish updates of these forward-looking statements.



Thank you

Growing Innovation

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